

**LISTING OF CLAIMS:**

1. (Previously Presented) An electro-optical modulator, comprising:  
a modulator chip having a low impedance and an RF electrode; and  
a microwave input chip coupled to the modulator chip, the microwave input chip having a thin film resistor for connecting an RF connector to the RF electrode of the modular chip, wherein the microwave input chip is configured to increase the total input impedance of the modulator.
2. (Previously Presented) The electro-optical modulator of Claim 1, wherein the modulator chip is a Lithium Niobate chip.
3. (Previously Presented) The electro-optical modulator of Claim 1, further comprising a microstrip line in the microwave input chip, the thin film resistor being placed in the microstrip line.
4. (Previously Presented) The electro-optical modulator of Claim 3, wherein the microstrip line is a straight line.
5. (Previously Presented) The electro-optical modulator of Claim 1, further comprising a coplanar waveguide in the microwave input chip, the thin film resistor being placed in the coplanar waveguide.
6. (Previously Presented) The electro-optical modulator of Claim 3, wherein the microstrip line is curved.
7. (Previously Presented) The electro-optical modulator of Claim 1, further comprising a plurality of bondings for coupling the microwave input chip to the modulator chip.
8. (Cancelled)

9. (Original) The electro-optical modulator of Claim 1, wherein the microwave input chip is manufactured with a substrate of Alumina, Gallium Arsenide, Aluminum Nitride or other type of substrates commonly used for microwave applications.
10. (Previously Presented) An electro-optical modulator, comprising:  
a modulator chip having a low impedance and an RF electrode; and  
a microwave input chip coupled to the modulator chip, the microwave input chip having a resistor member with a low impedance for increasing the total input impedance of the modulator, wherein the resistor member connects an RF connector to the RF electrode of the modular chip.
11. (Previously Presented) The electro-optical modulator of Claim 10, wherein the resistor member comprises a thin film resistor.
12. (Previously Presented) The electro-optical modulator of Claim 10, wherein the resistor member comprises a lumped resistance.
13. (Previously Presented) The electro-optical modulator of Claim 10, wherein the modulator chip is a Lithium Niobate chip.
14. (Previously Presented) The electro-optical modulator of Claim 10, further comprising a microstrip line or coplanar line in the microwave input chip, the resistor member being placed in the microstrip line.
15. (Previously Presented) The electro-optical modulator of Claim 14, wherein the microstrip line is a straight line.
16. (Previously Presented) The electro-optical modulator of Claim 10, further comprising a coplanar waveguide in the microwave input chip, the resistor member being placed in the coplanar waveguide.

17. (Previously Presented) The electro-optical modulator of Claim 14, wherein the microstrip line is curved.
18. (Previously Presented) The electro-optical modulator of Claim 10, further comprising a plurality of bondings for coupling the microwave input chip to the modulator chip.
19. (Cancelled)
20. (Original) The electro-optical modulator of Claim 10, wherein the microwave input chip is manufactured with a substrate of Alumina, Gallium Arsenide, Aluminum Nitride or other type of substrates commonly used for microwave applications.
21. (Previously Presented) The electro-optical modulator of Claim 1, wherein the thin film resistor has a resistance between 1-10 Ohms.
22. (Previously Presented) The electro-optical modulator of Claim 10, wherein the resistor member has a resistance between 1-10 Ohms.